

# 3D status @ FBK

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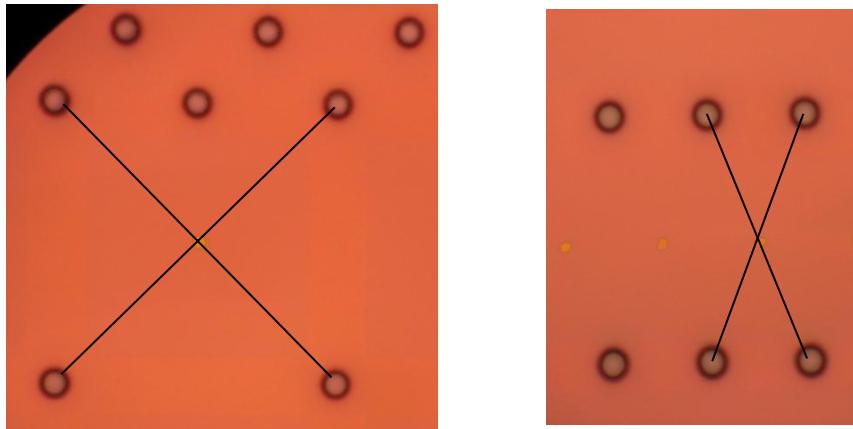
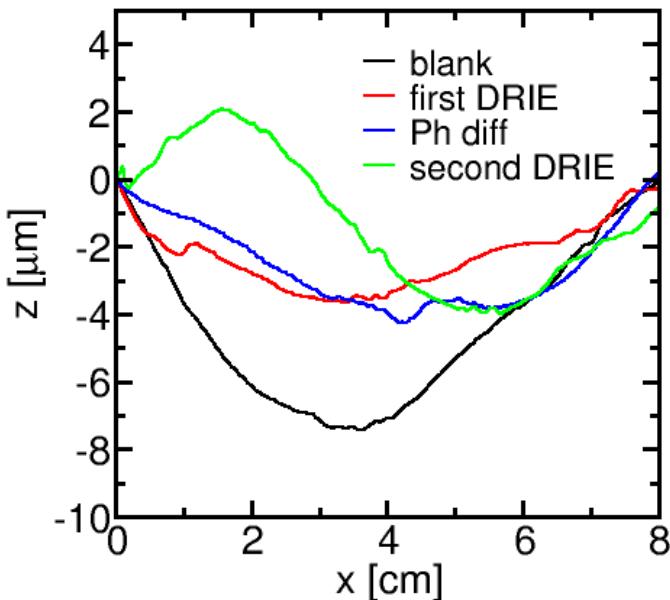
# 3D completed processes

Batch name	FE	No. of wafers	Wafer thickness [μm]	Comments	Status
Atlas 07	I4	4	230	bowig ~100μm	sent to IZM for bump-bonding
Atlas 07	I4	4	200	bowig ~100μm	electrical tests in progress
Atlas 08	I3	1	200	bowig <50μm	bump-bonding at Selex. Test in progress.
Atlas 08	I3	5	200	bowig <50μm	electrical tests in progress

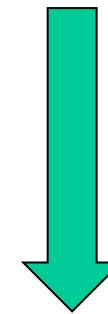
# 3D fabrication status

Batch name	FE	No. of wafers	Wafer thickness [μm]	Comments	Status
Atlas 09	I4	10	200	bowing<10μm	second DRIE done
		8	23		
		5	250		
Atlas 10	I4	25	230		edge protection
Atlas 10	I4	25	230		edge protection
AtlasIBL	I4	20	230+500	3D <u>with</u> support wafer	sent to sintef

# ATLAS09



- new process to further reduction of the bowing
- measure of the bowing step by step during the process



good columns alignment  
also at the wafer edge

# ATLAS07: IV measurements on 3D diodes

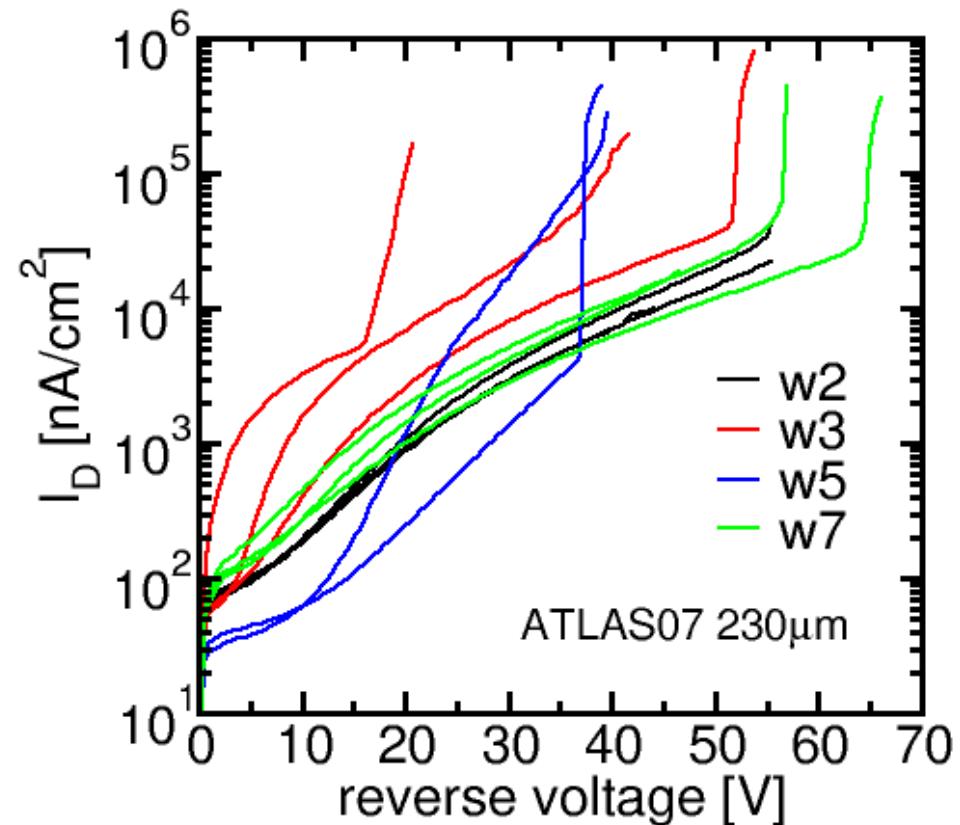
80\_BIG\_MOD

Area = 9.4 mm<sup>2</sup>

40X40 ohmic columns (p+)

39X39 Junction Columns (n+)

**~30pA/column @ 10V  
VBD~50-60V**



# ATLAS08: IV measurements on 3D diodes

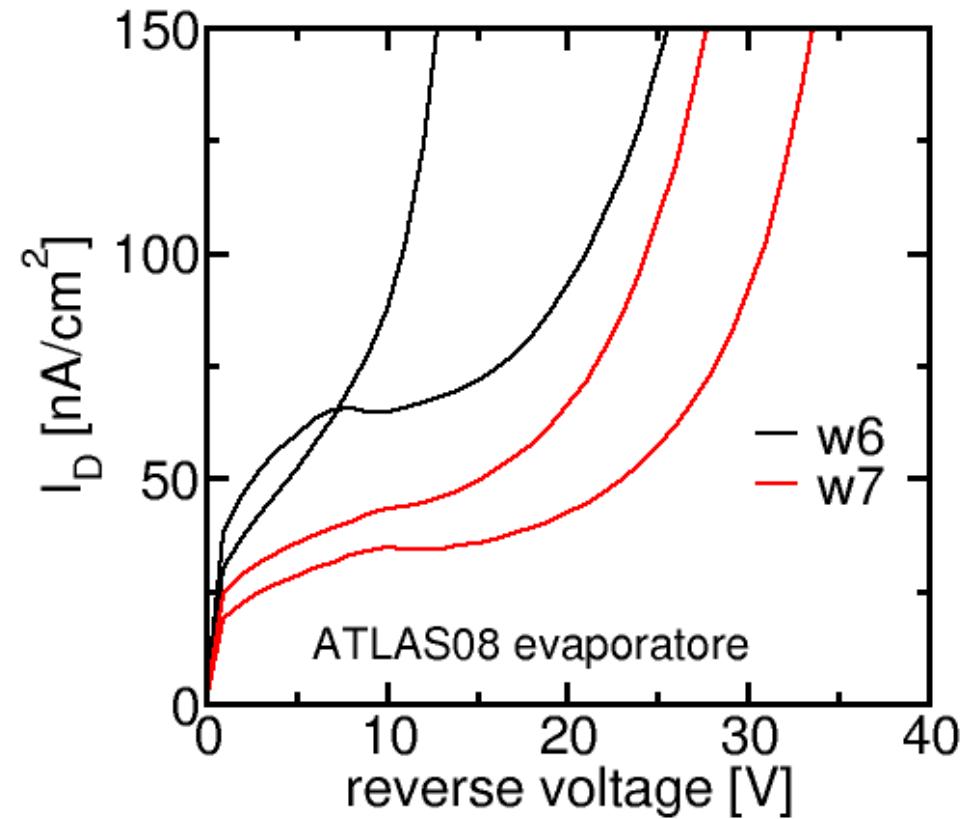
80\_BIG\_MOD

Area = 9.4 mm<sup>2</sup>

40X40 ohmic columns (p+)

39X39 Junction Columns (n+)

**~3pA/column @ 10V  
VBD~30-40V**



			28-feb-11	
			07-mar-11	
			14-mar-11	
			21-mar-11	
<b>ATLAS 09 200&amp;250</b>				
			colonne p+	
	isolamento	colonne p+		
		p&n plus		
			contatti	
<b>ATLAS 09 230</b>				
			contatti	
	isolamento	metal		
		colonne n+		
			passivazione	
<b>ATLAS 10</b>				
			metal	
	isolamento	colonne p+		
		p&n plus		
			contatti	
<b>ATLAS 11</b>				
			passivazione	
	isolamento	23-mag-11		
			30-mag-11	
			06-giu-11	
			13-giu-11	
			20-giu-11	
			27-giu-11	
			04-lug-11	
			11-lug-11	